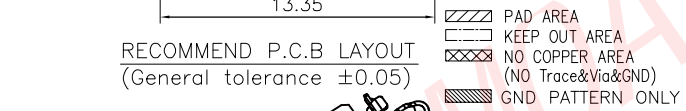
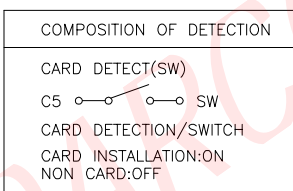
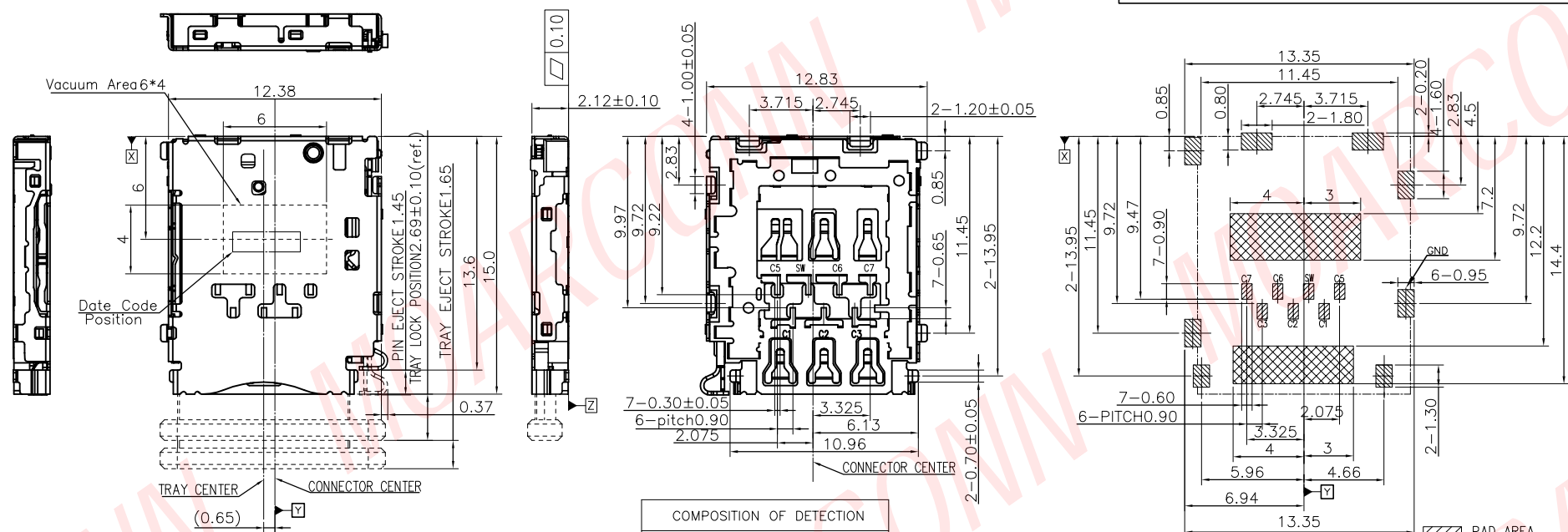


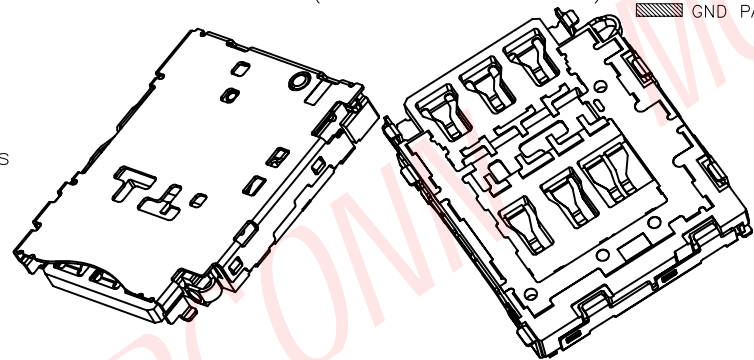
All materials, plating and process meet HF requirements.



- NOTE:
- Material:
    - 1-1 Housing: High Temperature Thermoplastic, (LCP S475) Color Black UL 94V-0
    - 1-2 Contact: Phosphor Bronze (C5210R-H, T=0.10±0.01mm)
    - 1-3 Cover: SUS301-H T=0.15±0.03mm
  - Plating:
    - 2-1 Contact terminal:
      - Contact area: Gold 1u" Min.
      - Solder area: Gold 0.8u" Min.
      - Underplating: Ni overall 50U" Min.
    - 2-2 Cover:
      - Underplating: Ni overall 30U" Min.
      - Solder area: Gold 0.8u" Min.
  - Specification:
    - 3-1. Current Rating :0.5A max.
    - 3-2. Contact Resistance: 50 mOhms max
    - 3-3. Insulation Resistance: 1000 MOhms min./500VDC
    - 3-4. Dielectric Withstanding Voltage: 500 V AC/1minute
    - 3-5. Operating Temperature: -25°C to +85°C
    - 3-6. Mating Cycles: 5000 Insertions
  - Product Compliant to RoHS Directive 2002/95/EC and ELV 2000/53/EC
  - Part Must Comply Taisol HF WD-3-I-091 Specification.
  - Recommending A Metal More Than 0.15mm Thick.  
Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.

SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA



		<b>DONG GUAN MOARCONN ELECTRONIC Co., Ltd.</b>			
		DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE	PRODUCT NAME : NANO SIM H2.15 CARD CONN(SMT)	DRAWING: janyz	DATE: 2018.11.19
DIMENSION TOLERANCE X.X: ± 0.35 X.XX: ± 0.20 X.XXX: ± 0.10 ANGULAR: ± 2'	PRODUCT NO. : NS215-T1131-01	CHECK:	DATE:		
	DRAWING NO. : D-NS215-T1131-01	APPROVED:	DATE:		
	SCALE: 1:1	DWG ID: C D	REV.: B	PAGE: 1 OF 1	

B	ECN20181119001	Modify the parameter	janyz	2018.11.19
A	----	NEW RELEASE	ping	2017.03.10
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE